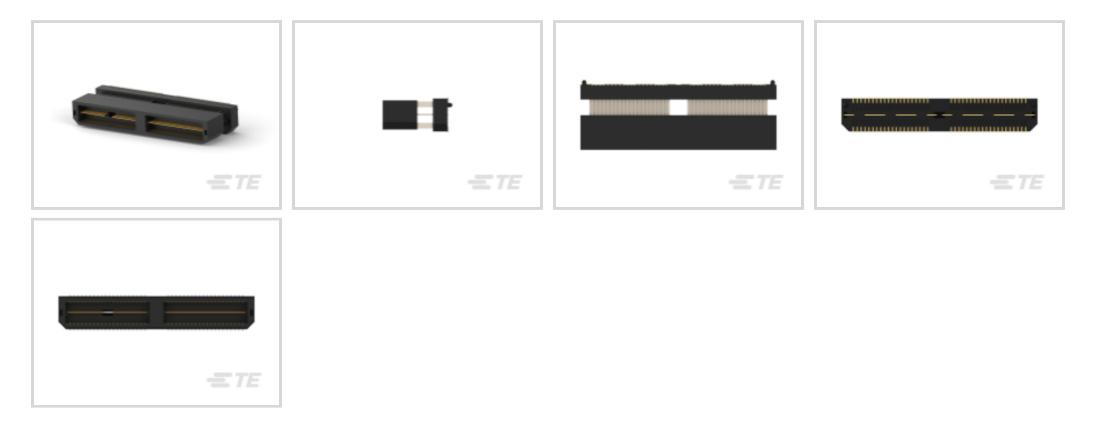


MICTOR

TE Internal #: 1658438-2 PCB Mount Header, Vertical, Board-to-Board, 80 Position, .8 mm [. 031 in] Centerline, Fully Shrouded, Gold Flash, Surface Mount, Power & Signal, Black

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: 80

Centerline (Pitch): .8 mm [.031 in]

Features



Product Type Features

PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Fully Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Stackable	No
Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Vertical
Number of Positions	80
Board-to-Board Configuration	Parallel
Electrical Characteristics	
Dielectric Withstanding Voltage (Max)	675 VAC
Insulation Resistance	2 ΜΩ

PCB Mount Header, Vertical, Board-to-Board, 80 Position, .8 mm [.031 in] Centerline, Fully Shrouded, Gold Flash, Surface Mount, Power & Signal, Black



Impedance Operating Voltage Body Features Primary Product Color Contact Features PCB Contact Termination Area Plating Material Thickness Mating Tab Width	100 Ω 125 VAC Black .25 μm[9.8425 μin] .38 mm[.015 in]
Body Features Primary Product Color Contact Features PCB Contact Termination Area Plating Material Thickness Mating Tab Width	Black .25 µm[9.8425 µin] .38 mm[.015 in]
Primary Product Color Contact Features PCB Contact Termination Area Plating Material Thickness Mating Tab Width	.25 μm[9.8425 μin] .38 mm[.015 in]
Contact Features PCB Contact Termination Area Plating Material Thickness Mating Tab Width	.25 μm[9.8425 μin] .38 mm[.015 in]
PCB Contact Termination Area Plating Material Thickness Mating Tab Width	.38 mm[.015 in]
Mating Tab Width	.38 mm[.015 in]
	2 mm[0.08 in]
Mating Tab Thickness	.2 mm[.008 in]
Contact Shape & Form	Single Beam, Square
PCB Contact Termination Area Plating Material	Gold
Contact Base Material	Phosphor Bronze
Contact Mating Area Plating Material	Gold Flash
	9.8425 µin
Contact Type	Pin
Contact Current Rating (Max)	1.25 A, 9.5 A
Termination Features	
Rectangular Termination Post & Tail Thickness	.2 mm[.008 in]
Rectangular Termination Post & Tail Width	.9 mm[.035 in]
Termination Method to Printed Circuit Board	Surface Mount
Mechanical Attachment	
PCB Mount Alignment Type	Locating Posts
Mating Retention	With
Mating Alignment	Without
PCB Mount Retention	With
PCB Mount Alignment	With
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	.8 mm[.031 in]
Housing Material	LCP (Liquid Crystal Polymer)
Dimensions	
Connector Height	13.39 mm[.526 in]
Stack Height	14 mm[.551 in]

PCB Mount Header, Vertical, Board-to-Board, 80 Position, .8 mm [.031 in] Centerline, Fully Shrouded, Gold Flash, Surface Mount, Power & Signal, Black



Usage Conditions

Operating Temperature Range	-65 – 125 °C[-85 – 257 °F]
Operation/Application	
Assembly Process Feature	None
Circuit Application	Power & Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	40
Packaging Type	Box, Tray
Product Compliance For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235)

(235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC

Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Solder Process Capability

Halogen Content

Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts

L For support call+1 800 522 6752

PCB Mount Header, Vertical, Board-to-Board, 80 Position, .8 mm [.031 in] Centerline, Fully Shrouded, Gold Flash, Surface Mount, Power & Signal, Black





Customers Also Bought



PCB Mount Header, Vertical, Board-to-Board, 80 Position, .8 mm [.031 in] Centerline, Fully Shrouded, Gold Flash, Surface Mount, Power & Signal, Black





Documents

Product Drawings MSB0.80PL14ASY080FL,-,10,-TY

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_1658438-2_J.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_1658438-2_J.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_1658438-2_J.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages MICTOR SB Interconnection System

English

Product Specifications Application Specification

English